



ABSTRACT



The present invention provides a method of producing solder balls 70, including:
a first step wherein core materials 11 are adhered to the surface 1a of a substrate 1 on which a first adhesive layer 5 is provided; a second step wherein a second adhesive layer 13 is formed on the surface 11a of the core materials 11; a third step wherein solder particles 14 are adhered to the surface of the second adhesive layer 13; a fourth step wherein the solder particles 14 are melted to form a solder layer 15; and a fifth step wherein the substrate 1 is removed from the core materials 11 to obtain solder balls.